	02-2	25-2008	FLH Ref. No.: 4	150100-0606
2-15-08			U.S. DEPARTMENT OF CO	
To the Honorable Commissioner of Pa 103		original documents or copy thereof.		
Name of conveying party Shingo NAKAGAWA Additional name(s) of conveying party(ies) attached?YesX_ No		2. Name and address or SONY CORPORAT 1-7-1 Konan, Minato Tokyo, 108-0075, Ja	TION U.S. PT	
3. Nature of conveyance: X Assignment Security Agreement Merger Change of Name Other Execution Date(s): December 14, 2007		Additional name(s) &	021508	_ No
 Application number(s) or patent number(s): If this document is being filed together with A. Patent Application No., filed. Additional numbers attached?Yes	a new application, the execu	tion date of the application	on is: <u>December 14, 2007.</u>	
5. Name and address of party to whom correspondence concerning document should be mailed:		6. Total number of applications and patents involved 1		
Name: WILLIAM S. FROMM: Internal Address: FROMMER LAWRENG 745 FIFTH AVENUE	CE & HAUG LLP	7. Total fee (37 CFR 3. X Enclosed Authorized to be	41) charged to deposit account 50-0320	\$ <u>40.00</u>
City: NEW YORK State:	Y Zip: 10151	Deposit account num (Attach duplicate cop	ber: by of this page if paying by deposit acc	count)
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 Statement and signature. To the best of my knowledge and belief, the 	foregoing information is tru-	e and correct and any atta	ched copy is a true copy of the original	document.
William S. Frommer, Reg. No. 25,506			February 15, 2008	
Name of Person Signing	ature	Date		
			Total number of pages including covattachments, and document:	ver sheet,
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PATENT REEL: 020560 FRAME: 0310

CMS Docket Number:

ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

DATA PROCESSING APPARATUS AND DATA PROCESSING METHOD

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan,

Minato-Ku, Tokyo, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: __ ____, Filing Date: ___ This assignment executed on the dates indicated below. Shingo NAKAGAWA Name of first or sole inventor Execution date of U.S. Patent Application Kanagawa, Japan Residence of first or sole inventor December 14, 2007 Signature of first or sole inventor Execution date of U.S. Patent Application Name of second inventor Residence of second inventor Date of this assignment Signature of second inventor Execution date of U.S. Patent Application Name of third inventor Residence of third inventor Date of this assignment

> **PATENT** REEL: 020560 FRAME: 0311

RECORDED: 02/15/2008

Signature of third inventor